4,194,304 WORD × 1 BIT DYNAMIC RAM

This is advanced information and specifications are subject to change without notice.

DESCRIPTION

The TC514101AP/AJ/ASJ/AZ is the new generation dynamic RAM organized 4,194,304 words by 1 bit. The TC514101AP/AJ/ASJ/AZ utilizes TOSHIBA's CMOS Silicon gate process technology as well as advanced circuit techniques to provide wide operating margins, both internally and to the system user. Multiplexed address inputs permit the TC514101AP/AJ/ASJ/AZ to be packaged in a standard 18 pin plastic DIP, 26/20 pin plastic SOJ(300/350mil) and 20 pin plastic ZIP. The package size provides high system bit densities and is compatible with widely available automated testing and insertion equipment. System oriented features include single power supply of 5V±10% tolerance, direct interfacing capability with high performance logic families such as Schottky TTL. The special feature of TC514101AP/AJ/ASJ/AZ is nibble mode, allowing the user to serially access 4 bits of data at a high data rate.

FEATURES

- 4,194,304 word by 1bit organization
- Fast access time and cycle time

		TC514101AP/AJ/ASJ/AZ - 60
trac	RAS Access Time	60ns
† _{AA}	Column Address Access Time	30ns
tcac	CAS Access Time	20ns
t _{RC}	Cycle Time	110ns
^t NCAC	Nibble Mode Access Time	20ns
t _{NC}	Nibble Mode Cycle Time	40ns

• Single power supply of 5V±10% with a built-in VBB generator

• Low Power

660mW MAX. Operating (TC514101AP/AJ/ASJ/AZ -- 60) 5.5mW MAX. Standby

- Output unlatched at cycle end allows twodimensional chip selection
- Common I/O capability using "EARLY WRITE" operation
- Read-Modify-Write, CAS before RAS refresh, RAS-only refresh, Hidden refresh, Nibble Mode and Test Mode capability
- All inputs and output TTL compatible
- 1024 refresh cycles/16ms
- Package TC514101AP :

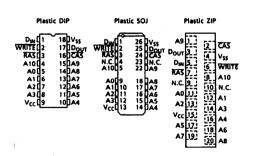
: DIP18-P-300E : SOJ26-P-350

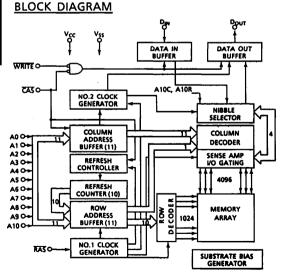
TC514101AJ : SOJ26-P-350 TC514101ASJ : SOJ26-P-300A TC514101AZ : ZIP20-P-400A

PIN NAMES

A0~A10	Address Inputs	WRITE	Read/Write Input
CAS	Column Address Strobe	Vcc	Power (+ 5V)
D _{IN}	Data In	Vss	Ground
D _{OUT}	Data Out	N.C.	No Connection
RAS	Row Address Strobe		

PIN CONNECTION (TOP VIEW)





ABSOLUTE MAXIMUM RATINGS

ITEM	SYMBOL	RATING	UNITS	NOTES
Input Voltage	Vin	- 1~7	V	1
Output Voltage	V _{OUT}	- 1~7	٧	1
Power Supply Voltage	Vcc	- 1~7	٧	1
Operating Temperature	T _{OPR}	0~70	۰c	1
Storage Temperature	T _{STG}	- 55~150	°C	1
Soldering Temperature · Time	TSOLDER	260 · 10	°C · sec	1
Power Dissipation	PD	700	mW	1
Short Circuit Output Current	lout	50	mA	1

RECOMMENDED DC OPERATING CONDITIONS ($Ta = 0 \sim 70^{\circ}C$)

SYMBOL	PARAMETER	MIN.	TYP.	MAX.	UNIT	NOTES
Vcc	Supply Voltage	4.5	5.0	5.5	V	2
VIH	Input High Voltage	2.4	-	6.5	V	2
V _{IL}	Input Low Voltage	- 1.0	-	0.8	٧	2

DC ELECTRICAL CHARACTERISTICS ($V_{CC} = 5V \pm 10\%$, $Ta = 0 \sim 70$ °c)

SYMBOL	PARAMETER		MIN.	MAX.	UNITS	NOTES
I _{CC1}	OPERATING CURRENT Average Power Supply Operating Current $(\overline{RAS}, \overline{CAS}, Address Cycling: t_{RC} = t_{RC} MIN.)$	rC514101AP/AJ/ASJ/AZ-60	-	120	mA	3, 4 5
Iccz	STANDBY CURRENT Power Supply Standby Current (RAS = CAS = V _{IH})		<u>-</u>	2	mA	
l _{CC3}	\overline{RAS} ONLY REFRESH CURRENT Average Power Supply Current, \overline{RAS} Only Mode (\overline{RAS} Cycling, $\overline{CAS} = V_{IH}$: $t_{RC} = t_{RC}$ MIN.)	TC514101AP/AJ/ASJ/AZ-60	-	120	mA	3,5
¹ cc4	NIBBLE MODE CURRENT Average Power Supply Current, Nibble Mode (RAS = V _{IL} , CAS, Cycling: t _{NC} = t _{NC} MIN.)	TC514101AP/AJ/ASJ/AZ-60	-	50	mA	3, 4 5
Iccs	STANDBY CURRENT Power Supply Standby Current (RAS = CAS = V _{CC} - 0.2V)		_	1	mA	
I _{CC6}	$\overline{\text{CAS}}$ BEFORE $\overline{\text{RAS}}$ REFRESH CURRENT Average Power Supply Current, $\overline{\text{CAS}}$ Before $\overline{\text{RAS}}$ Mode ($\overline{\text{RAS}}$, $\overline{\text{CAS}}$ Cycling: $t_{\text{RC}} = t_{\text{RC}}$ MIN.)	TC514101AP/AJ/ASJ/AZ-60	-	120	mA	3, 5
l ₁ (L)	INPUT LEAKAGE CURRENT Input Leakage Current, any input $(0V \le V_{IN} \le 6.5V, All Other Pins Not Under Test = 0V)$		- 10	10	μA	
lo (L)	OUTPUT LEAKAGE CURRENT (D _{OUT} is disabled, 0V≤V _{OUT} ≤5.5V)		- 10	10	μΑ	
V _{ОН}	OUTPUT LEVEL Output "H" Level Voltage (I _{OUT} = -5mA)		2.4	-	v	
Vol	OUTPUT LEVEL Output "L" Level Voltage (I _{OUT} = 4.2mA)		1	0.4	v	



ELECTRICAL CHARACTERISTICS AND RECOMMENDED AC OPERATING CONDITIONS $(V_{CC} = 5V \pm 10\%, Ta = 0 \sim 70^{\circ}c)(Notes 6, 7, 8)$

SYMBOL	DARAMETER	TC514101AP/	AJ/ASJ/AZ-60	LINUT	NOTES
STIVIBUL	PARAMETER	MIN.	MAX.	UNII	
t _{RC}	Random Read or Write Cycle Time	110	_	ns	
t _{RMW}	Read-Modify-Write Cycle Time	135	-	ns	
t _{NC}	Nibble Mode Cycle Time	40	-	ns	
t _{NRMW}	Nibble Mode ReadModify Write Cycle Time	65		ns	
t _{RAC}	Access Time from RAS	-	60	ns	9,14 15
t _{CAC}	Access Time from CAS	-	20	ns	9,14
taa	Access Time from Column Address	-	30	ns	9,15
t _{NCAC}	Nibble Mode Access Time	-	20	ns	9
t _{CLZ}	CAS to Output in Low-Z	0	-	ns	9
toff	Output Buffer Turn-off Delay	0	20	ns	10
t _T	Transition Time (Rise and Fall)	` 3	50	ns	8
t _{RP}	RAS Precharge Time	40	-	ns	
t _{RAS}	RAS Pulse Width	60	10,000	ns	
t _{RSH}	RAS Hold Time	20	-	ns	
tcsH	CAS Hold Time	60	-	ns	
t _{CAS}	CAS Pulse Width	20	10,000	ns	
t _{RCD}	RAS to CAS Delay Time	20	40	ns	14
trad	RAS to Column Address Delay Time	15	30	ns	15
t _{CRP}	CAS to RAS Precharge Time	5	-	ns	
t _{CP}	CAS Precharge Time	10	-	ns	
tasr	Row Address Set-Up Time	0	-	ns	
t _{RAH}	Row Address Hold Time	10	-	ns	
t _{ASC}	Column Address Set-Up Time	0	-	ns	
t _{CAH}	Column Address Hold Time	15	-	ns	
t _{RAL}	Column Address to RAS Lead Time	30	-	ns	
t _{RCS}	Read Command Set-Up Time	0	-	ns	
t _{RCH}	Read Command Hold Time referenced to CAS	0	-	ns	11
t _{RRH}	Read Command Hold Time referenced to RAS	0	-	ns	11
twcH	Write Command Hold Time	10	_	ns	
t _{WP}	Write Command Pulse Width	10	-	ns	
t _{RWL}	Write Command to RAS Lead Time	20		ns	
t _{CWL}	Write Command to CAS Lead Time	20		ns	
tos	Data-In Set-Up Time	0		ns	12

ELECTRICAL CHARACTERISTICS AND RECOMMENDED AC OPERATING CONDITIONS (Continued)

SYMBOL	PARAMETER	TC514101AP/	LIAUTE	NOTES	
ZAMROL		MIN.	MAX.		NOTES
t _{DH}	Data-In Hold Time	15		ns	12
tREF	Refresh Period	-	16	ms	
twcs	Write Command Set-UP Time	0	1	ns	13
t _{CWD}	CAS to WRITE Delay Time	20	-	ns	13
t _{RWD}	RAS to WRITE Delay Time	60	-	ns	13
t _{AWD}	Column Address to WRITE Delay Time	30	-	ns	13
t _{CSR}	CAS Set-Up Time (CAS before RAS)	5	-	ns	
t _{CHR}	CAS Hold Time (CAS before RAS)	15	-	ns	
t _{RPC}	RAS Precharge to CAS Active Time	0	-	ns	
t _{CPT}	CAS Precharge Time (CAS before RAS Counter Test)	30	-	ns	
t _{NCAS}	Nibble Mode Pulse Width	20	-	ns	
t _{NCP}	Nibble Mode CAS Precharge Time	10	-	ns	
t _{NRSH}	Nibble Mode RAS Hold Time	20	-	ns	
t _{NCWD}	Nibble Mode CAS to WRITE Delay Time	20	-	ns	
t _{NRWL}	Nibble Mode WRITE Command to RAS Lead Time	20	-	ns	
t _{NCWL}	Nibble Mode WRITE Command to CAS Lead Time	20	_	ns	
t _{WTS}	Write Command Set-Up Time (Test Mode In)	10	-	ns	
t _{WTH}	Write Command Hold Time (Test Mode In)	10	-	ns	
t _{WRP}	WRITE to RAS Precharge Time (CAS before RAS Cycle)	10	-	ns	
t _{WRH}	WRITE to RAS Hold Time (CAS before RAS Cycle)	10	-	ns	



ELECTRICAL CHARACTERISTICS AND RECOMMENDED AC OPERATION CONDITIONS IN THE TEST MODE (Vcc = $5V \pm 10\%$, Ta = $0 \sim 70$ °C) (Note6, 7, 8)

SYMBOL	PARAMETER	TC514101AP	TC514101AP/AJ/ASJ/AZ-60		
		MIN.	MAX.		NOTES
t _{RC}	Random Read or Write Cycle Time	115	-	ns	
t _{RAC}	Access Time from RAS	-	65	ns	9,14, 15
t _{CAC}	Access Time from CAS	-	25	ns	9,14
taa	Access Time from Column Address	-	35	ns	9,15
tras	RAS Pulse Width	65	10,000	ns	
t _{RSH}	RAS Hold Time	25	-	ns	
t _{CSH}	CAS Hold Time	65	-	ns	
t _{CAS}	CAS Pulse Width	25	10,000	ns	
^t ral	Column Address to RAS Lead Time	35	-	ns	

CAPACITANCE ($V_{CC} = 5V \pm 10\%$, f = 1MHz, $Ta = 0 \sim 70$ °C)

SYMBOL	PARAMETER	MIN.	MAX.	UNIT
C _{I1}	Input Capacitance (A0~A10, D _{IN})	-	5	
C ₁₂	Input Capacitance (RAS, CAS, WRITE)	-	7	ρF
Co	Output Capacitance (D _{OUT})	-	7	

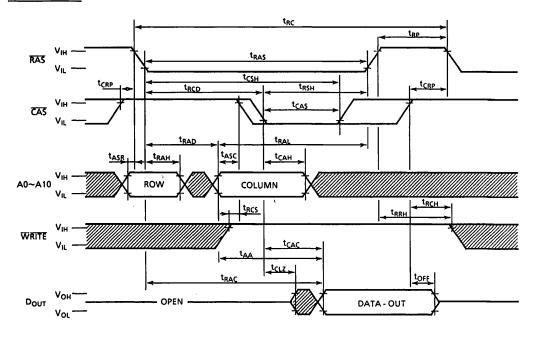
NOTES:

- 1. Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device.
- 2. All voltages are referenced to VSS.
- 3. ICC1, ICC3, ICC4, ICC6 depend on cycle rate.
- 4. ICC1, ICC4 depend on output loading. Specified values are obtained with the output open.
- 5. Column address can be changed once or less While RAS=VIL and CAS=VIH.
- 6. An initial pause of 200μs is required after power-up followed by 8 RAS only refresh cycles before proper device operation is achieved. In case of using internal refresh counter, a minimum of 8 CAS before RAS refresh cycles instead of 8 RAS only refresh cycles are required.
- 7. AC measurements assume t_T=5ns.
- 8. V_{IH} (min.) and V_{IL} (max.) are reference levels for measuring timing of input signals. Also, transition times are measured between V_{IH} and V_{IL}.
- 9. Measured with a load equivalent to 2 TTL loads and 100pF.
- 10. toff (max.) defines the time at which the output achieves the open circuit condition and is not referenced to output voltage levels.
- 11. Either tRCH or tRRH must be satisfied for a read cycle.
- 12. These parameters are referenced to CAS leading edge in early write cycles and to WRITE leading edge in read-write cycles.
- 13. twcs, trwd, tcwd and tawd are not restrictive operating parameters. They are included in the data sheet as electrical characteristics only. If twcs≥twcs (min.), the cycle is an early write cycle and data out pin will remain open circuit (high impedance) throughout the entire cycle; If trwd≥trwd (min.), tcwd≥tcwd (min.) and trwd≥trwd (min.) the cycle is a read-write cycle and the data out will contain data read from the selected cell: If neither of the above sets of conditions is satisfied, the condition of the data out (at access time) is indeterminate.
- 14. Operation within the t_{RCD} (max.) limit insures that t_{RAC} (max.) can be met. t_{RCD} (max.) is specified as a reference point only: If t_{RCD} is greater than the specified t_{RCD} (max.) limit, then access time is controlled by t_{CAC}.
- 15. Operation within the t_{RAD} (max.) limit insures that t_{RAC} (max.) can be met. t_{RAD} (max.) is specified as a reference point only: If t_{RAD} is greater than the specified t_{RAD} (max.) limit, then access time is controlled by t_{AA}.



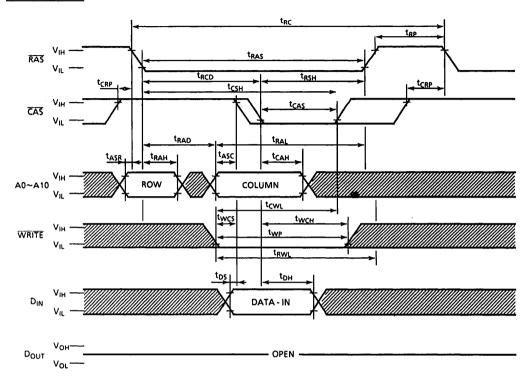
TIMING WAVEFORMS

READ CYCLE



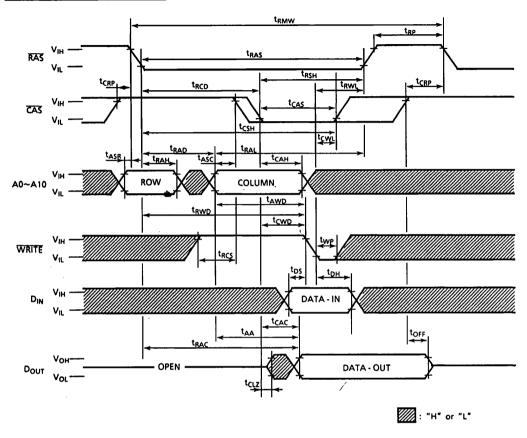
: "H" or "L"

WRITE CYCLE (EARLY WRITE)

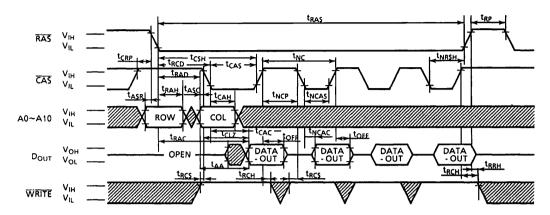




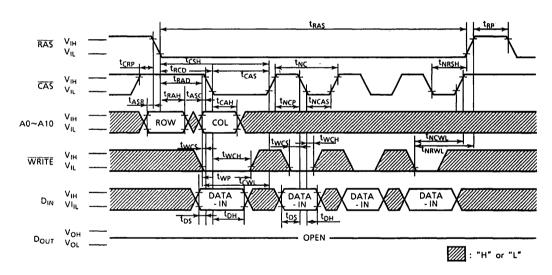
READ-MODIFY-WRITE CYCLE



NIBBLE MODE READ CYCLE

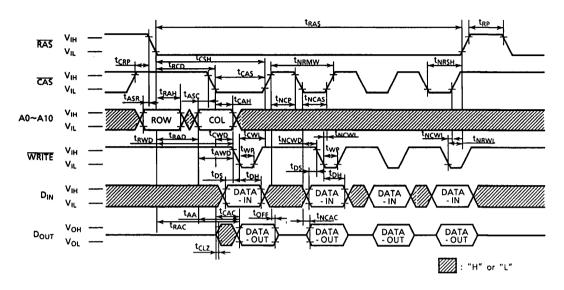


NIBBLE MODE WRITE CYCLE(EARLY WRITE)

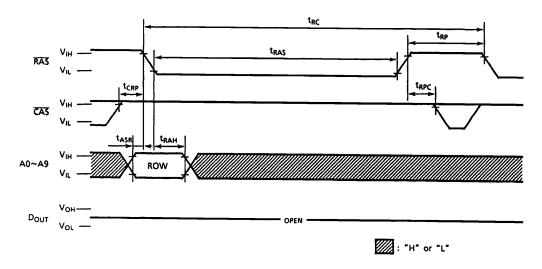




NIBBLE MODE READ - MODIFY - WRITE



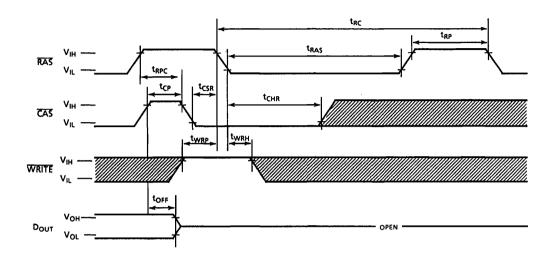
RAS ONLY REFRESH CYCLE



Note: WRITE = "II" or "L" A10 = "H" or "L"

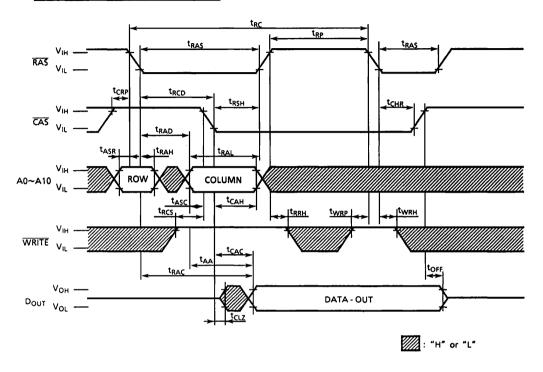


CAS BEFORE RAS REFRESH CYCLE

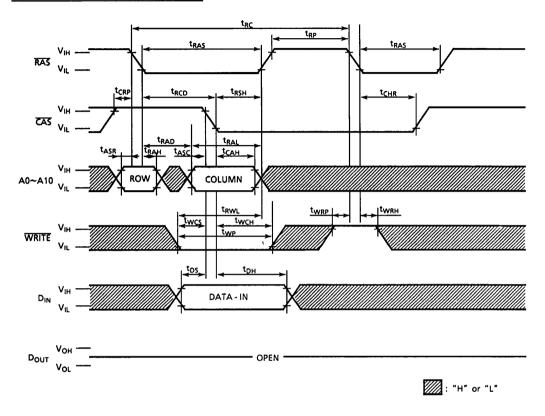


Note: A0~A10="H" or "L" : "H" or "L"

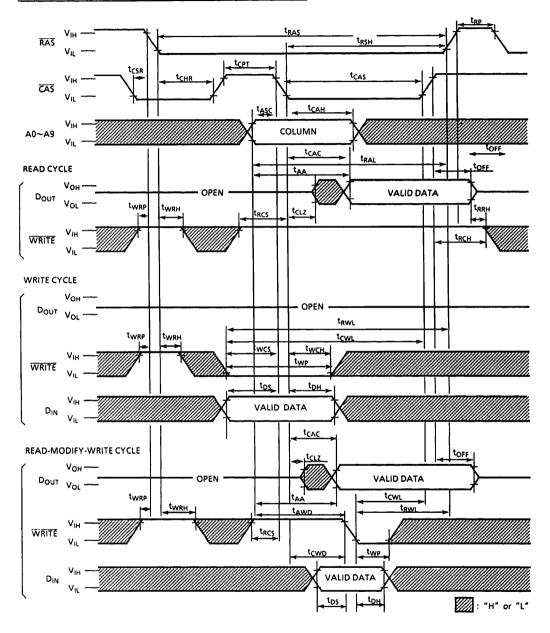
HIDDEN REFRESH CYCLE (READ)



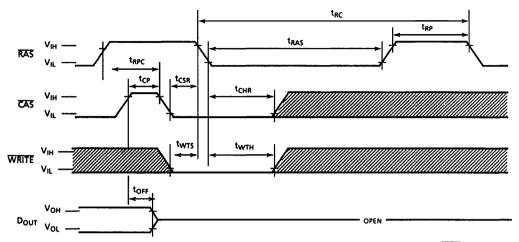
HIDDEN REFRESH CYCLE (WRITE)



CAS BEFORE RAS REFRESH COUNTER TEST CYCLE



WRITE, CAS BEFORE RAS REFRESH CYCLE



APPLICATION INFORMATION

ADDRESSING

The 22 address bits required to decode 1 of the 4,194,304 cell locations within the TC514101AP/AJ/ASJ/AZ are multiplexed onto the 11 address inputs and latched into the on-chip address latches by externally applying two negative going TTL-level clocks.

The first clock, the Row Address Strobe (RAS), latches the 11 row address bits into the chip. The second clock, the Column Address Strobe (CAS), subsequently latches the 11 column address bits into the chip. Each of these signals, RAS, and CAS, triggers a sequence of events which are controlled by different delayed internal clocks.

The two clock chains are linked together logically in such a way that the address multiplexing operation is done outside of the critical path timing sequence for read data access. The later events in the \overline{CAS} clock sequence are inhibited until the occurrence of a delayed signal derived from the \overline{RAS} clock chain. The "gated \overline{CAS} " feature allows the \overline{CAS} clock to be externally activated as soon as the Row Address Hold Time specification (t_{RAII}) has been satisfied and the address inputs have been changed from Row address to Column address information.

DATA INPUT/OUTPUT

Data to be written into a selected cell is latched into an on-chip register by a combination of WRITE and \overline{CAS} While \overline{RAS} is active. The later of the signals (WRITE or \overline{CAS}) to make its negative transition is the strobe for the Data In (D_{IN}) register. This permits several options in the write cycle timing. In a write cycle, if the \overline{WRITE} input is brought low (active) prior to \overline{CAS} , the D_{IN} is strobed by \overline{CAS} and the set-up and hold times are referenced to \overline{CAS} . If the input data is not available at \overline{CAS} time or if it is desired that the cycle be a read-write cycle, the \overline{WRITE} signal will be delayed until after \overline{CAS} has made its negative transition. In this "delayed write cycle"the data input set-up and hold times are referenced to the negative edge of \overline{WRITE} rather than \overline{CAS} . (To illustrate this feature, D_{IN} is referenced to \overline{WRITE} in the timing diagrams depicting the read-modify-write and nibble mode write cycles while the "early write" cycle diagram shows D_{IN} referenced to \overline{CAS}).

Data is retrieved from the memory in a read cycle by maintaining WRITE in the inactive or high state throughout the portion of the memory cycle in which \overline{CAS} is active (low). Data read from the selected cell will be available at the output within the specified access time.

DATA OUTPUT CONTROL

The normal condition of the Data Output (D_{OUT}) of the TC514101AP/AJ/ASJ/AZ is the high impedance (open circuit) state. This is to say, anytime CAS is at a high level, the D_{OUT} pin will be floating. The only time the output will turn on and contain either a logic 0 or logic 1 is at access time during a read cycle. D_{OUT} will remain valid from access time until CAS is taken back to the inactive (high level) condition.

NIBBLE MODE

Nibble mode operation allows faster successive data operation on 4 bits The first of 4 bits is accessed in the usual manner with read data coming out at t_{CAC} time. By keeping RAS low, CAS can be cycled up and then down, to read or write the next three pages at high data rate (faster than t_{CAC}). Row and column addresses need only be supplied for the first access of the cycles. From then on, the falling edge of CAS will activate the next bit. After four bits have been accessed, the next bit will be the same as the first bit accessed (wraparound method).



$$(0,0) \longrightarrow (0,1) \longrightarrow (1,0) \longrightarrow (1,1)$$

Address A10 determines the starting point of the circular 4 bits nibble. Row A10 and column A10 provide the two binary bits needed to select one of four bits.

From then on, successive bits come out in a binary fashion; $00 \rightarrow 01 \rightarrow 10 \rightarrow 11$ with A10 row being the least significant address.

A nibble cycle can be a read, write, or delayed write cycle. Any conbinations of reads and writes or late writes will be allowed. In addition, the circular wraparound will continue for as long as RAS is kept low.

RAS ONLY REFRESH

Refresh of the dynamic cell matrix is accomplished by performing a memory cycle at each of the 1024 row address (A0~A9) within each 16 millisecond time interval.

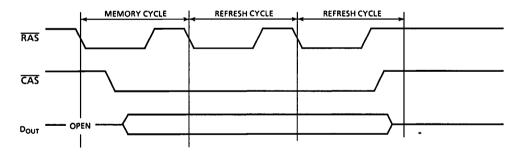
Although any normal memory cycle will perform the refresh operation, this function is most easily accomplished with "RAS-only" cycles.

CAS BEFORE RAS REFRESH

CAS before RAS refreshing available on the TC514101AP/AJ/ASJ/AZ offers an alternate refresh method. If CAS is held on low for the specified period (t_{CSR}) before RAS goes to low, on chip refresh control clock generators and the refresh address counter are enabled, and an internal refresh operation takes place. After the refresh operation is performed, the refresh address counter is automatically incremented in preparation for the next CAS before RAS refresh operation.

HIDDEN REFRESH

An optional feature of the TC514101AP/AJ/ASJ/AZ is that refresh cycles may be performed while maintaining valid data at the output pin. This referred to as Hidden Refresh. Hidden Refresh is performed by holding \overline{CAS} at V_{IL} and taking \overline{RAS} high and after a specified precharge period (t_{RP}), executing a \overline{CAS} before \overline{RAS} refresh cycle. (see Figure below)



This feature allows a refresh cycle to be "hidden" among data cycles without affecting the data avilability.

CAS BEFORE RAS REFRESH COUNTER TEST

The internal refresh operation of TC514101AP/AJ/ASJ/AZ can be tested by CAS BEFORE RAS REFRESH COUNTER TEST. This cycle performs READ/WRITE operation taking the internal counter address as row address and the input address as column address.

The test is performed after a minimum of 8 CAS before RAS cycles as initialization cycles. The test procedure is as follows.

- ① Write "0" into all the memory cells at normal write mode.
- ② Select one certain column address and read "0" out and write "1" in each cell by performing CAS BEFORE RAS REFRESH COUNTER TEST (READ-WRITE CYCLE). Repeat this operation 1024 times.
- 3 Check "1" out of 1024 bits at normal read mode, which was written at 2.
- ① Using the same column as ②, read "1" out and write "0" in each cell performing CAS BEFORE RAS REFRESH COUNTER TEST. Repeat this operation 1024 times.
- ⑤ Check "0" out of 1024 bits at normal read mode, which was written at ④.
- 6 Perform the above 1 to 5 to the complement data.



TEST MODE

The TC514101AP/AJ/ASJ/AZ is the RAM organized 4,194,304words by 1 bit, it is internally organized 524,288 words by 8 bits. In "Test Mode", data are written into 8 sectors in parallel and retrieved the same way. A10R, A10C and A0C are not used. If, upon reading, all bits are equal (all "1"s or" 0"s), the data output pin indicates a "1". If any of the bits differed, the data outputpin would indcate shows the block diagram of TC514101AP/ASJ/AZ. In "Test Mode", the 4M DRAM can be tested as if it were a 512K DRAM.

"WRITE, CAS Before RAS Refresh Cycle" puts the device "Test Mode". And "CAS Before RAS Refresh Cycle" or RAS Only Refresh Cycle" puts it back into "Normal Mode". In the Test Mode, "WRITE. CAS Before RAS Refresh Cycle" performs the refresh operation with the internal refresh address counter. The "Test Mode" function reduces test times (1/8 in case of N test pattern)

BLOCK DIAGRAM IN THE TEST MODE

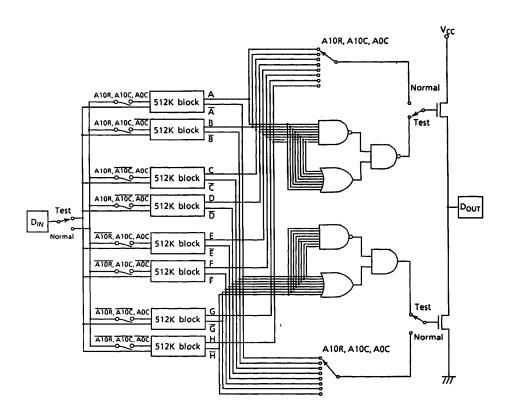


Fig. 1

